



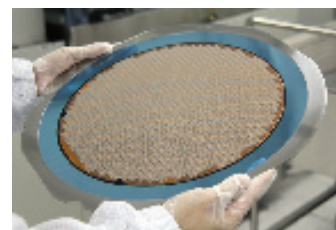
## About STATS ChipPAC

STATS ChipPAC (SGX-ST: STATSchP) is a leading service provider of semiconductor packaging design, bump, probe, assembly, test and distribution solutions. We have the scale to provide a comprehensive range of semiconductor packaging and test solutions to a diversified global customer base servicing the computing, communications and consumer markets.

## Technology and Services

With a broad technology portfolio ranging from leadframe to laminate, flip chip, wafer level and advanced 3D packaging solutions, STATS ChipPAC provides innovative and cost effective semiconductor solutions. STATS ChipPAC has a leadership position in advanced package technology including fan-in and fan-out wafer-level packaging, flip chip interconnect, 3D integration and Through Silicon Via (TSV) to meet the increasing market demand for next-generation devices with higher levels of integration, increased functionality and compact sizes.

As a full turnkey service provider, STATS ChipPAC provides wafer probe and final testing on a diverse selection of testers covering the major test platforms in the industry and has proven expertise in testing a broad range of semiconductors, especially mixed-signal, radio frequency (RF), analog and high-performance digital devices.



## Business Highlights

### Operations

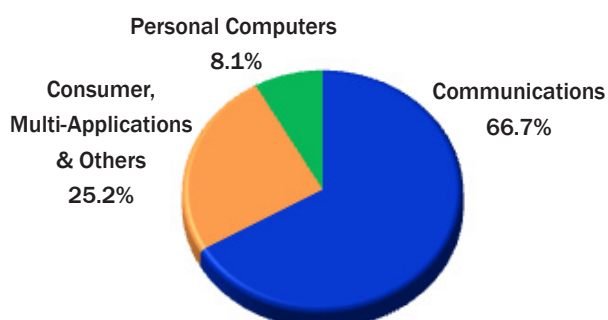
STATS ChipPAC's manufacturing facilities are located in strategic semiconductor markets including South Korea, Singapore, China, Malaysia and Taiwan. Our close proximity to the major hubs of wafer fabrication allows us to provide customers with fully-integrated, multi-site packaging and test services.

We market our services through a direct sales force and customer support teams in the United States, Singapore, South Korea, Japan, China, Taiwan and Switzerland.

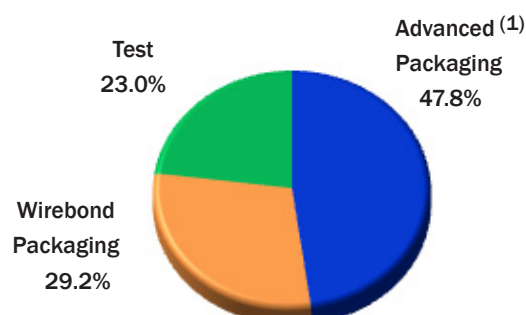


Note: 4,088 wire bonders and 959 testers as of 4Q 2013

### 4Q 2013 Revenue by End User Market



### 4Q 2013 Revenue by Product Line



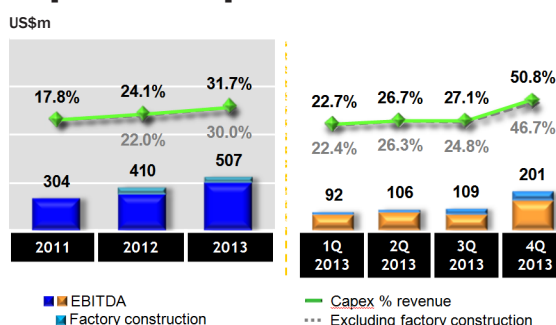
(1) Advanced Packaging includes flip chip and wafer level packaging.

## Financial Highlights

### 4Q 2013 Financial Results

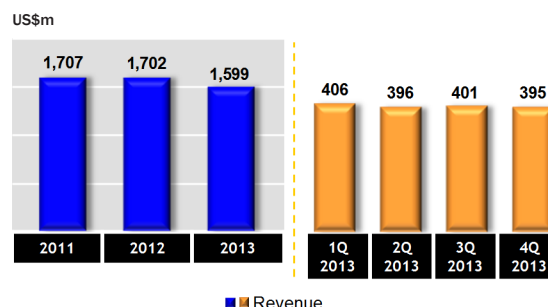
- Revenue decreased 1.4% sequentially, strength in wireless communications offset by seasonal weakness in computing and consumer markets
- Advanced packaging at 48% of our revenue, growth in wafer level packaging from eWLB traction and technology migration to wafer level products

### Capex and Capex as % of Revenue <sup>(2)</sup>

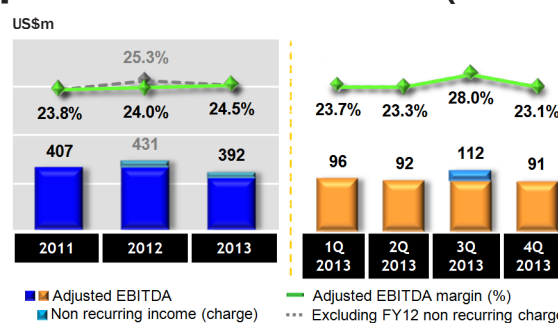


Note: (2) Capex for FY 2012, FY 2013, 1Q 2013, 2Q 2013, 3Q 2013 and 4Q 2013 included investments for the factory construction in Singapore of \$33.8 million, \$0.01 million, \$0.01 million, nil, nil and nil, respectively, and new factory in Korea of \$1.4 million, \$28.6 million, \$1.6 million, \$1.5 million, \$9.4 million and \$16.2 million, respectively.

### Revenue



### Adjusted Earnings Before Interest, Taxes, Depreciation and Amortization (EBITDA) <sup>(3) (4)</sup>



Note: (3) Adjusted EBITDA represents EBITDA plus (i) restructuring charges, (ii) share-based compensation, (iii) goodwill and equipment impairment, (iv) tender offer expenses, (v) debt exchange or debt redemption, (vi) write-off of debt issuance cost, and (vii) plant closure costs related to our Malaysia plant and our restructuring actions. Adjusted EBITDA includes non-recurring income (charges) primarily on insurance claims in FY 2012 and FY 2013, and litigation settlements in FY 2012, respectively.

(4) Excluding non-recurring charges, adjusted EBITDA in FY 2012 was \$430.9M or 25.3% of revenue, respectively

## Recent Headlines

- 21 Jan 14 STATS ChipPAC Recognised for Patent Innovations for the Third Consecutive Year by IEEE
- 30 Sep 13 STATS ChipPAC Provides Update on Insurance Recovery
- 19 Aug 13 STATS ChipPAC Delivers Industry Leading Ultra Thin Package-on-Package Solutions with eWLB Packaging
- 13 Aug 13 STATS ChipPAC and Nanyang Technological University Collaborate on New Innovative Packaging Technologies

## Corporate Information

### Executive Management

Tan Lay Koon, Director, President and Chief Executive Officer  
 Wan Choong Hoe, Executive VP and Chief Operating Officer  
 Dr. Han Byung Joon, Executive VP and Chief Technology Officer  
 Hal Lasky, Executive VP and Chief Sales Officer  
 John Lau Tai Chong, Senior VP and Chief Financial Officer  
 Janet Taylor, Senior VP, General Counsel and Company Secretary  
 Chong Khin Mien, Senior VP, Product and Technology Marketing

### Investor Relations Contact

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### Corporate Headquarters

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### Stock Information

Singapore Exchange Securities  
 Trading Limited (SGX-ST)  
 Ticker: STATSchP

